Claim 11, line 22, amend "." to --,--.

Claim 11, line 29, amend ";" to --.--.

Claim 12, line 15, delete "first".

Claim 12, line 28, amend ";" to --.--.

Please cancel claims 13 and 14 without prejudice.

Please add new claims 32-45 as follows:

32. (New) An illumination optical apparatus according to claim 21, further comprising: a conversion member for converting plural light-source-images formed by said optical integrator into a light-source-image having a ring shape or a light-source-image of which center is shifted from an optical axis of optical system of said illumination optical apparatus.

33. (New) An illumination optical apparatus according to claim 22, further comprising: a conversion member for converting plural light-source-images formed by said optical integrator into a light-source-image having a ring shape or a light-source-image of which center is shifted from an optical axis of optical system of said illumination optical apparatus.

34. (New) An illumination optical apparatus according to claim 23, further comprising: a conversion member for converting plural light-source-images formed by said optical integrator into a light-source-image having a ring shape or a light-source-image of which center is shifted from

an optical axis of optical system of said illumination optical apparatus.

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35. (New) An illumination optical apparatus according to claim 24, further comprising: a conversion member for converting plural light-source-images formed by said optical integrator into a light-source-image having a ring shape or a light-source-image of which center is shifted from an optical axis of optical system of said illumination optical apparatus.

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36. (New) A method of fabricating a semiconductor device using an illumination optical apparatus according to claim 1, said method comprising the steps of:

guiding a light from said illumination apparatus to a mask on which a predetermined circuit pattern is formed and illuminating the pattern; and

with moving said mask and photo-sensitive substrate in predetermined directions respectively, projecting said pattern of the mask on the sensitive substrate.

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37. (New) A method of fabricating a semiconductor device using an illumination optical apparatus according to claim 2, said method comprising the steps of:

guiding a light from said illumination apparatus to a mask on which a predetermined circuit pattern is formed and illuminating the patter; and

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with moving said mask and photo-sensitive substrate in predetermined directions respectively, projecting said pattern of the mask on the sensitive substrate.

38. (New) A method of fabricating a semiconductor device using an illumination optical apparatus according to claim 4, said method comprising the steps of:

guiding a light from said illumination apparatus to a mask on which a predetermined circuit pattern is formed and illuminating the pattern; and

with moving said mask and photo-sensitive substrate in predetermined directions respectively, projecting said pattern of the mask on the sensitive substrate.

39. (New) A method of fabricating a semiconductor device using a scanning exposure apparatus according to claim 17, said method comprising the steps of:

guiding a light from said condenser optical system to a said reticle and illuminating said reticle; and

with moving said reticle stage and said wafer stage in predetermined directions respectively, projecting a pattern of said reticle on said wafer to perform the exposure.

40. (New) A method of fabricating a semiconductor device using a scanning exposure apparatus according to claim 19, said method comprising the steps of:

guiding a light from said condenser optical system to a said reticle and illuminating said reticle; and

with moving said reticle stage and said wafer stage in predetermined directions respectively, projecting a pattern of said reticle on said wafer to perform the exposure.

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41. (New) A method of fabricating a semiconductor device using an illumination optical apparatus according to claim 24, said method comprising the steps of:

guiding a light from said illumination apparatus to a mask on which a predetermined circuit pattern is formed and illuminating the pattern; and

with moving said mask and photo-sensitive substrate in predetermined directions respectively, projecting said pattern of the mask on the sensitive substrate.

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42. (New) A method of fabricating a semiconductor device using an illumination optical apparatus according to claim 29, said method comprising the steps of:

guiding a light from said illumination apparatus to a mask on which a predetermined circuit pattern is formed and illuminating the pattern; and

with moving said mask and photo-sensitive substrate in predetermined directions respectively, projecting said pattern of the mask on the sensitive substrate.

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43. (New) A method of fabricating a semiconductor device using a scanning exposure apparatus according to claim 33, said method comprising the steps of:

guiding a light from said condenser optical system to said reticle to illuminate said reticle; and

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